

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

SEKO, Toshiharu

Atty. Ref.: 925-214

Serial No. unknown

Group:

Filed: October 12, 2001

Examiner:

For: TAPE FOR CHIP ON FILM AND SEMICONDUCTOR THEREWITH

* * * * *

October 12, 2001

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

PRELIMINARY AMENDMENT

Please amend the above-identified application as follows:

IN THE CLAIMS

Please substitute the following amended claim 18 for the corresponding claim 18 previously presented. A copy of the amended claim 18 showing current revisions is attached.

099506-1001
"FOR" 9905260

18. A semiconductor device comprising a semiconductor element mounted on the tape for chip on film as defined in Claim 1 and sealed with resin.

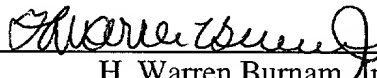
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REMARKS

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page/s is/are captioned "**Version With Markings To Show Changes Made.**"

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

18. A semiconductor device comprising a semiconductor element mounted on the tape for chip on film as defined in ~~any one of~~ Claims 1 to 17 and sealed with resin.